

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): **Kale (et al.)**

Attorney Docket: **0025-013**

Serial No.: **10/784,102**

Examiner: **Durnford-Geszvain, Dillon**

Filed: **February 20, 2004**

Group Art Unit: **2622**

Title: **Integrated Lens And Chip Assembly For A Digital Camera**

MS RCE

Commissioner for Patents

Customer No.: **40972**

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**INFORMATION DISCLOSURE STATEMENT**

Pursuant to 37 C.F.R. §1.56, §1.97, and §1.98, Applicants bring the following documents to the Examiner's attention in the above-referenced application:

1. U.S. Patent No. 4,894,707, issued January 16, 1990, to Yamawaki et al.;
2. U.S. Patent No. 6,122,009, issued September 19, 2000, to Ueda;
3. U.S. Patent App. 2002/0145676, dated October 10, 2002, by Kuno et al.;
4. U.S. Patent App. 2003/0071342, dated April 17, 2003, by Honda et al.;
5. U.S. Patent No. 6,686,588, issued February 3, 2004, to Webster et al.;
6. U.S. Patent App. 2004/0027687, dated February 12, 2004, by Bittner et al.;
7. U.S. Patent App. 2005/0046740, dated March 3, 2005, by Davis;
8. U.S. Patent App. 2005/0274883, dated December 15, 2005, by Nagano;
9. U.S. Patent App. 2006/0006486, dated January 12, 2006, by Seo et al.;
10. U.S. Patent App. 2006/0028573, dated February 9, 2006, by Seo et al.;
11. U.S. Patent App. 2006/0044450, dated March 2, 2006, by Wolterink et al.;
12. E.P. Patent App. 0 813 236, dated December 17, 1997, by European Semiconductor Assembly;
13. J.P. Patent App. 2001-292365, dated October 19, 2001, by Mitsubishi Electric Corp. (English Abstract Included);
14. U.S. Patent No. 7,061,106, issued June 13, 2006, to Yang et al.;
15. U.S. Patent App. 2006/0132644, dated June 22, 2006, by Shangguan et al.; and

16. U.S. Patent App. 2007/0058069, dated March 15, 2007, by Chen et al.

A PTO form 1449 listing these documents is enclosed. The relevance of the attached references is that they were cited in related cases.

English abstracts are provided to satisfy the requirement for a concise explanation of the relevance of the non-English references, as provided for in M.P.E.P. §609.04(a)(III).

Citation of the above documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b).

This information disclosure statement is filed with a Request for Continued Examination. Therefore, no fee is due. 37 CFR §1.97(b)(4).

Respectfully Submitted,

Date: February 27, 2009

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**CERTIFICATE OF MAILING OR TRANSMISSION**

I hereby certify that this correspondence (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: MS RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450, or is being facsimile transmitted to the U.S. Patent and Trademark Office, or is being electronically filed with the U.S. Patent and Trademark Office on the date shown below.

Date: February 27, 2009

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